

Title (en)
ELECTRICALLY CONDUCTING MATERIAL WITH COATING

Title (de)
ELEKTRISCH LEITENDES MATERIAL MIT BESCHICHTUNG

Title (fr)
MATÉRIAU ÉLECTROCONDUCTEUR AVEC REVÊTEMENT

Publication
EP 4225960 A1 20230816 (DE)

Application
EP 20838897 A 20201221

Priority
• DE 102020006059 A 20201005
• EP 2020000215 W 20201221

Abstract (en)
[origin: WO2022073575A1] The invention relates to an electrically conducting material (1) comprising a substrate (10) of copper or a copper alloy and a coating (2) of at least one layer (21, 22), wherein the coating (2) has an outermost layer (21) of which at least 90% by volume consists of an intermetallic phase (41) which comprises or is Cu₆Sn₅. According to the invention, the surface of the outermost layer (21) facing away from the substrate (10) has isolated silver-rich precipitates (3) covering a proportion of the surface area of 7 to 20%.

IPC 8 full level
C23C 2/08 (2006.01); **C22C 13/00** (2006.01); **C22F 1/08** (2006.01); **C23C 2/04** (2006.01); **C23C 2/28** (2006.01); **C23C 28/02** (2006.01); **C23C 30/00** (2006.01); **C25D 5/50** (2006.01); **H01R 13/03** (2006.01)

CPC (source: EP KR US)
B32B 15/01 (2013.01 - US); **B32B 15/04** (2013.01 - US); **B32B 15/043** (2013.01 - US); **B32B 15/20** (2013.01 - US); **C22C 9/00** (2013.01 - US); **C22C 9/02** (2013.01 - US); **C22C 13/00** (2013.01 - EP KR US); **C22C 30/02** (2013.01 - US); **C22C 30/04** (2013.01 - US); **C22F 1/08** (2013.01 - EP KR US); **C23C 2/08** (2013.01 - EP KR US); **C23C 28/021** (2013.01 - US); **C23C 28/023** (2013.01 - EP KR US); **C23C 28/027** (2013.01 - EP KR US); **C23C 30/00** (2013.01 - EP KR US); **C23C 30/005** (2013.01 - US); **Y10T 428/12431** (2015.01 - US); **Y10T 428/12438** (2015.01 - US); **Y10T 428/12896** (2015.01 - US); **Y10T 428/12903** (2015.01 - US); **Y10T 428/1291** (2015.01 - US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
DE 102020006059 A1 20220407; CN 116075601 A 20230505; EP 4225960 A1 20230816; JP 2023546769 A 20231108; KR 20230080393 A 20230607; US 12071692 B2 20240827; US 2023265549 A1 20230824; WO 2022073575 A1 20220414

DOCDB simple family (application)
DE 102020006059 A 20201005; CN 202080104274 A 20201221; EP 2020000215 W 20201221; EP 20838897 A 20201221; JP 2023504741 A 20201221; KR 20237005619 A 20201221; US 202018040169 A 20201221